

Dual Buffer

NL27WZ16

The NL27WZ16 is a high performance dual buffer operating from a 1.65 V to 5.5 V Supply.

Features

- Designed for 1.65 V to 5.5 V V_{CC} Operation
- 2.4 ns t_{PD} at V_{CC} = 5 V (Typ)
- Inputs/Outputs Overvoltage Tolerant up to 5.5 V
- I_{OFF} Supports Partial Power Down Protection
- Sink 32 mA at 4.5 V
- Available in SC-88, SC-74 and UDFN6 Packages
- Chip Complexity < 100 FETs
- –Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

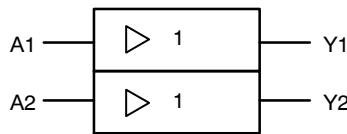
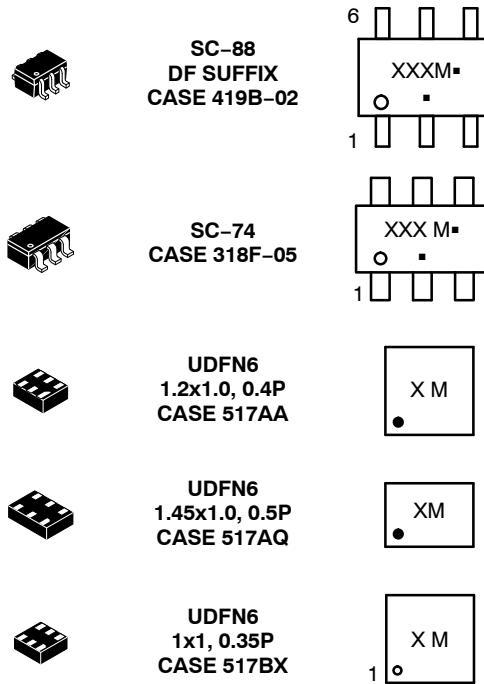


Figure 1. Logic Symbol

MARKING DIAGRAMS



X, XXX = Specific Device Code

M = Date Code*

▪ = Pb-Free Package

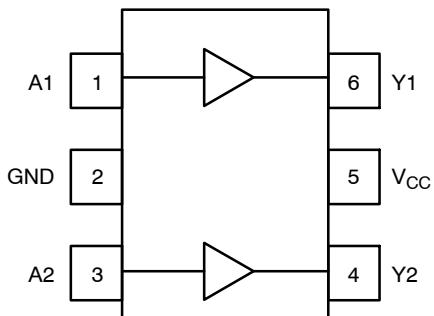
(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

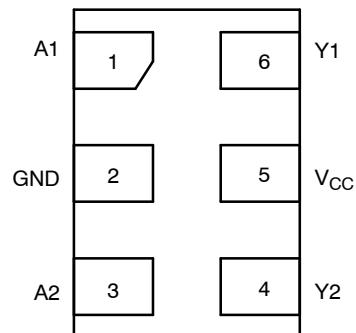
ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

NL27WZ16



(SC-88 / SC-74)



UDFN6

Figure 2. Pinout (Top View)

PIN ASSIGNMENT

Pin	Function
1	A1
2	GND
3	A2
4	Y2
5	V _{CC}
6	Y1

FUNCTION TABLE

A Input	Y Output
L	L
H	H

MAXIMUM RATINGS

Symbol	Characteristics	Value	Units
V_{CC}	DC Supply Voltage	-0.5 to +6.5	V
V_{IN}	DC Input Voltage	-0.5 to +6.5	V
V_{OUT}	DC Output Voltage SC-88, SC-74, UDFN6	Active-Mode (High or Low State) Tri-State Mode (Note 1) Power-Down Mode ($V_{CC} = 0$ V)	-0.5 to $V_{CC} + 0.5$ -0.5 to +6.5 -0.5 to +6.5
I_{IK}	DC Input Diode Current, $V_{IN} < GND$	-50	mA
I_{OK}	DC Output Diode Current, $V_{OUT} < GND$	-50	mA
I_{OUT}	DC Output Source/Sink Current	± 50	mA
I_{CC} or I_{GND}	DC Supply Current per Supply Pin or Ground Pin	± 100	mA
T_{STG}	Storage Temperature Range	-65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 secs	260	°C
T_J	Junction Temperature under Bias	+150	°C
θ_{JA}	Thermal Resistance (Note 2)	SC-88 SC-74 UDFN6	377 320 154
P_D	Power Dissipation in Still Air	SC-88 SC-74 UDFN6	332 390 812
MSL	Moisture Sensitivity	Level 1	-
F_R	Flameability Rating	Oxygen Index: 28 to 34	UL 94-V-0 @ 0.125 in
V_{ESD}	ESD Withstand Voltage (Note 3)	Human Body Model Charged Device Model (NLV) Charged Device Model	2000 1000 N/A
$I_{LATCHUP}$	Latchup Performance (Note 4)	± 100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Applicable to devices with outputs that may be tri-stated.
2. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow per JESD51-7.
3. HBM tested to ANSI/ESDA/JEDEC JS-001-2017. CDM tested to EIA/JESD22-C101-F. JEDEC recommends that ESD qualification to EIA/JESD22-A115-A (Machine Model) be discontinued per JEDEC/JEP172A.
4. Tested to EIA/JESD78 Class II.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
V_{CC}	Positive DC Supply Voltage	1.65	5.5	V	
V_{IN}	DC Input Voltage	0	5.5	V	
V_{OUT}	DC Output Voltage	0 0 0	V_{CC} 5.5 5.5	V	
T_A	Operating Temperature Range	-55	+125	°C	
t_r, t_f	Input Transition Rise or Fall Rate	$V_{CC} = 1.65$ V to 1.95 V $V_{CC} = 2.3$ V to 2.7 V $V_{CC} = 3.0$ V to 3.6 V $V_{CC} = 4.5$ V to 5.5 V	0 0 0 0	20 20 10 5	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Condition	V _{CC} (V)	T _A = 25°C			-55°C ≤ T _A ≤ 125°C		Units
				Min	Typ	Max	Min	Max	
V _{IH}	High-Level Input Voltage		1.65 to 1.95	0.65 × V _{CC}			0.65 × V _{CC}		V
			2.3 to 5.5	0.70 × V _{CC}			0.70 × V _{CC}		
V _{IL}	Low-Level Input Voltage		1.65 to 1.95			0.35 × V _{CC}		0.35 × V _{CC}	V
			2.3 to 5.5			0.30 × V _{CC}		0.30 × V _{CC}	
V _{OH}	High-Level Output Voltage	V _{IN} = V _{IH} or V _{IL}	1.65 to 5.5	V _{CC} - 0.1	V _{CC}	–	V _{CC} - 0.1	–	V
		I _{OH} = -100 µA	1.65	1.29	1.4	–	1.29	–	
		I _{OH} = -4 mA	2.3	1.9	2.1	–	1.9	–	
		I _{OH} = -8 mA	2.7	2.2	2.4	–	2.2	–	
		I _{OH} = -12 mA	3.0	2.4	2.7	–	2.4	–	
		I _{OH} = -16 mA	3.0	2.3	2.5	–	2.3	–	
		I _{OH} = -24 mA	3.0	2.3	2.5	–	2.3	–	
		I _{OH} = -32 mA	4.5	3.8	4.0	–	3.8	–	
V _{OL}	Low-Level Output Voltage	V _{IN} = V _{IH} or V _{IL}	1.65 to 5.5	–	–	0.1	–	0.1	V
		I _{OL} = 100 µA	1.65	–	0.08	0.24	–	0.24	
		I _{OL} = 4 mA	2.3	–	0.2	0.3	–	0.3	
		I _{OL} = 8 mA	2.7	–	0.22	0.4	–	0.4	
		I _{OL} = 12 mA	3.0	–	0.28	0.4	–	0.4	
		I _{OL} = 16 mA	3.0	–	0.38	0.55	–	0.55	
		I _{OL} = 24 mA	3.0	–	0.42	0.55	–	0.55	
		I _{OL} = 32 mA	4.5	–	0.42	0.55	–	0.55	
I _{IN}	Input Leakage Current	V _{IN} = 5.5 V or GND	1.65 to 5.5	–	–	±0.1	–	±1.0	µA
I _{OFF}	Power Off Leakage Current	V _{IN} = 5.5 V or V _{OUT} = 5.5 V	0	–	–	1.0	–	10	µA
I _{CC}	Quiescent Supply Current	V _{IN} = V _{CC} or GND	5.5	–	–	1.0	–	10	µA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

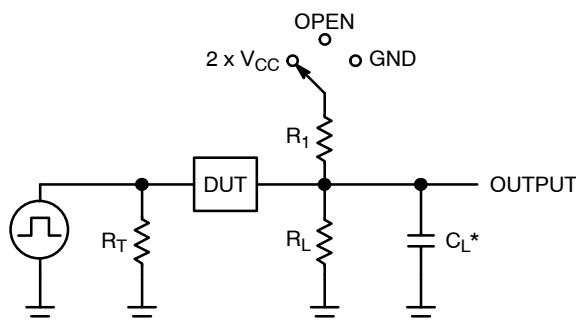
AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Condition	V _{CC} (V)	T _A = 25°C			−40°C ≤ T _A ≤ 85°C		−55°C ≤ T _A ≤ 125°C		Unit
				Min	Typ	Max	Min	Max	Min	Max	
t _{PLH} , t _{PHL}	Propagation Delay, A to Y (Figures 3 and 4)	RL = 1 MΩ, CL = 15 pF	1.65 to 1.95	–	8.0	9.6	–	10.2	–	10.2	ns
		RL = 1 MΩ, CL = 15 pF	2.3 to 2.7	–	3.0	5.2	–	5.8	–	5.8	
			3.0 to 3.6	–	2.3	3.6	–	4.0	–	4.0	
			4.5 to 5.5	–	1.8	2.9	–	3.2	–	3.2	
		RL = 500 Ω, CL = 50 pF	3.0 to 3.6	–	3.0	4.6	–	5.1	–	5.1	
			4.5 to 5.5	–	2.4	3.8	–	4.2	–	4.2	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C_{IN}	Input Capacitance	$V_{CC} = 5.5 \text{ V}$, $V_I = 0 \text{ V}$ or V_{CC}	2.5	pF
C_{OUT}	Output Capacitance	$V_{CC} = 5.5 \text{ V}$, $V_I = 0 \text{ V}$ or V_{CC}	4.0	pF
C_{PD}	Power Dissipation Capacitance (Note 5)	10 MHz, $V_{CC} = 3.3 \text{ V}$, $V_{IN} = 0 \text{ V}$ or V_{CC} 10 MHz, $V_{CC} = 5.0 \text{ V}$, $V_{IN} = 0 \text{ V}$ or V_{CC}	11 12.5	pF

5. CPD is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = CPD \cdot V_{CC} \cdot f_{IN}$. I_{CC} . CPD is used to determine the no-load dynamic power consumption; $P_D = CPD \cdot V_{CC}^2 \cdot f_{IN}$. $I_{CC} \cdot V_{CC}$.



C_L includes probe and jig capacitance
 R_T is Z_{OUT} of pulse generator (typically 50 Ω)
 $f = 1$ MHz

Figure 3. Test Circuit

Test	Switch Position	C_L , pF	R_L , Ω	R_1 , Ω
t_{PLH} / t_{PHL}	Open	See AC Characteristics Table		
t_{PLZ} / t_{PZL}	$2 \times V_{CC}$	50	500	500
t_{PHZ} / t_{PZH}	GND	50	500	500

X = Don't Care

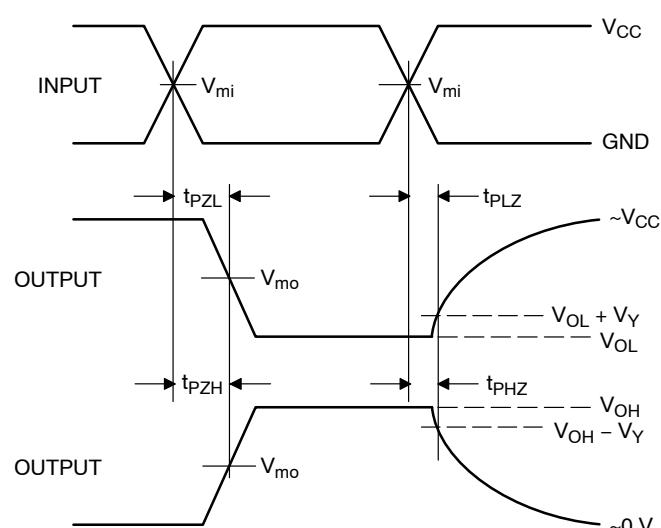
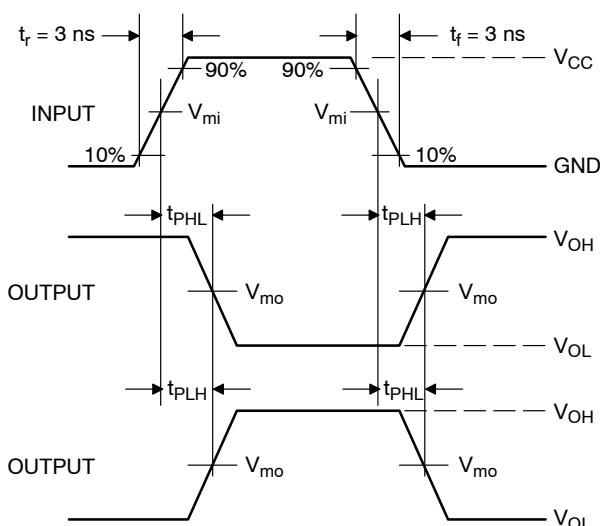


Figure 4. Switching Waveforms

V_{CC} , V	V_{mi} , V	V_{mo} , V		V_Y , V
		t_{PLH}, t_{PHL}	$t_{PZL}, t_{PLZ}, t_{PZH}, t_{PHZ}$	
1.65 to 1.95	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	0.15
2.3 to 2.7	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	0.15
3.0 to 3.6	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	0.3
4.5 to 5.5	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	0.3

NL27WZ16

ORDERING INFORMATION

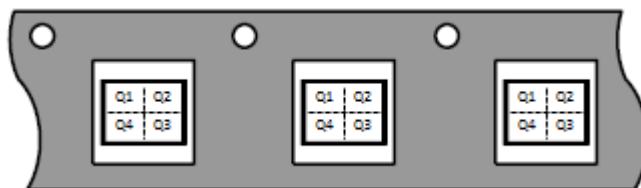
Device	Package	Specific Device Code	Pin1 Orientation (See below)	Shipping [†]
NL27WZ16DFT2G	SC-88	MR	Q4	3000 / Tape & Reel
NL27WZ16DFT2G-Q*	SC-88	MR	Q4	3000 / Tape & Reel
NL27WZ16DBVT1G	SC-74	MR	Q4	3000 / Tape & Reel
NL27WZ16MU1TCG	UDFN6, 1.45 x 1.0, 0.5P	F (Rotated 90° CW)	Q4	3000 / Tape & Reel
NL27WZ16MU3TCG	UDFN6, 1.0 x 1.0, 0.35P	T (Rotated 90° CW)	Q4	3000 / Tape & Reel
NL27WZ16MU2TCG	UDFN6, 1.2 x 1.0, 0.4P	5 (Rotated 180° CW)	Q4	3000 / Tape & Reel

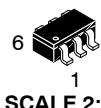
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*-Q Suffix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

Pin 1 Orientation in Tape and Reel

Direction of Feed

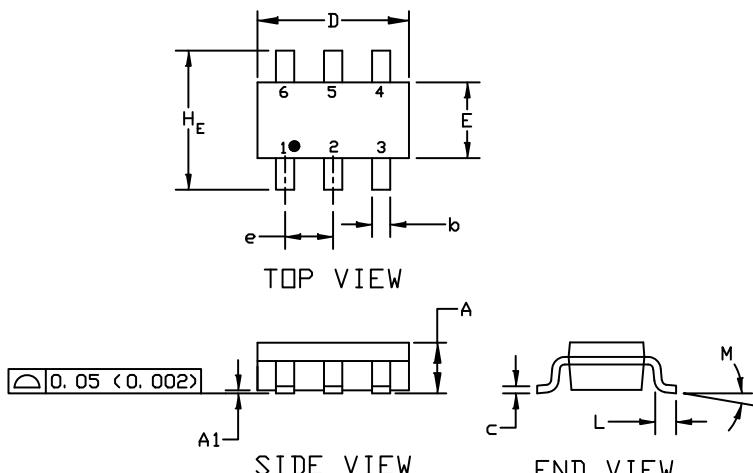




SCALE 2:1

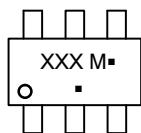
SC-74
CASE 318F
ISSUE P

DATE 07 OCT 2021



NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994
 2. CONTROLLING DIMENSION: INCHES
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.

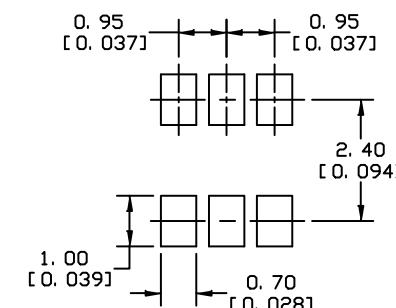
DIM	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.90	1.00	1.10	0.035	0.039	0.043
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.25	0.37	0.50	0.010	0.015	0.020
c	0.10	0.18	0.26	0.004	0.007	0.010
D	2.90	3.00	3.10	0.114	0.118	0.122
E	1.30	1.50	1.70	0.051	0.059	0.067
e	0.85	0.95	1.05	0.034	0.037	0.041
H _E	2.50	2.75	3.00	0.099	0.108	0.118
L	0.20	0.40	0.60	0.008	0.016	0.024
M	0°	---	10°	0°	---	10°

GENERIC
MARKING DIAGRAM*

XXX = Specific Device Code
 M = Date Code
 □ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.



* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

SOLDERING FOOTPRINT

STYLE 1:	STYLE 2:	STYLE 3:	STYLE 4:	STYLE 5:	STYLE 6:
PIN 1. CATHODE	PIN 1. NO CONNECTION	PIN 1. Emitter 1	PIN 1. Collector 2	PIN 1. CHANNEL 1	PIN 1. CATHODE
2. ANODE	2. COLLECTOR	2. BASE 1	2. Emitter 1/Emitter 2	2. ANODE	2. ANODE
3. CATHODE	3. Emitter	3. COLLECTOR 2	3. COLLECTOR 1	3. CHANNEL 2	3. CATHODE
4. CATHODE	4. NO CONNECTION	4. Emitter 2	4. Emitter 3	4. CHANNEL 3	4. CATHODE
5. ANODE	5. COLLECTOR	5. BASE 2	5. BASE 1/BASE 2/Collector 3	5. CATHODE	5. CATHODE
6. CATHODE	6. BASE	6. COLLECTOR 1	6. BASE 3	6. CHANNEL 4	6. CATHODE

STYLE 7:	STYLE 8:	STYLE 9:	STYLE 10:	STYLE 11:
PIN 1. SOURCE 1	PIN 1. Emitter 1	PIN 1. Emitter 2	PIN 1. ANODE/CATHODE	PIN 1. Emitter
2. GATE 1	2. BASE 2	2. BASE 2	2. BASE	2. BASE
3. DRAIN 2	3. COLLECTOR 2	3. COLLECTOR 1	3. Emitter	3. ANODE/CATHODE
4. SOURCE 2	4. Emitter 2	4. Emitter 1	4. COLLECTOR	4. ANODE
5. GATE 2	5. BASE 1	5. BASE 1	5. ANODE	5. CATHODE
6. DRAIN 1	6. COLLECTOR 1	6. COLLECTOR 2	6. CATHODE	6. COLLECTOR

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DESCRIPTION:	SC-74	PAGE 1 OF 1

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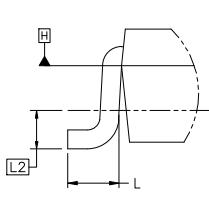
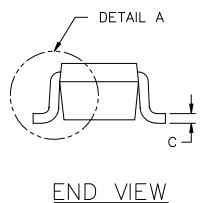
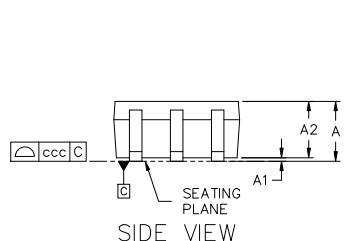
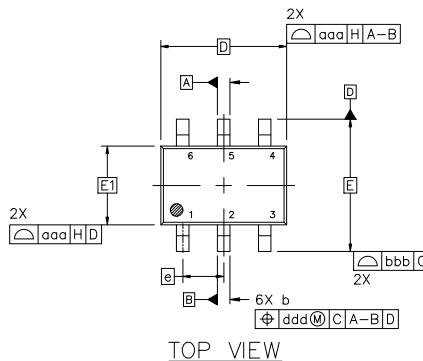


SC-88 2.00x1.25x0.90, 0.65P
CASE 419B-02
ISSUE Z

DATE 18 APR 2024

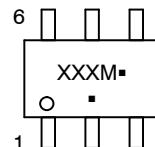
NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5-2018.
2. ALL DIMENSION ARE IN MILLIMETERS.
3. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END.
4. DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AND DATUM H.
5. DATUM A AND B ARE DETERMINED AT DATUM H.
6. DIMENSIONS b AND c APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP.
7. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION b AT MAXIMUM MATERIAL CONDITION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	1.10
A1	0.00	---	0.10
A2	0.70	0.90	1.00
b	0.15	0.20	0.25
c	0.08	0.15	0.22
D	2.00	BSC	
E	2.10	BSC	
E1	1.25	BSC	
e	0.65	BSC	
L	0.26	0.36	0.46
L2	0.15	BSC	
aaa	0.15		
bbb	0.30		
ccc	0.10		
ddd	0.10		

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

XXX = Specific Dev.

■ = Ph-Free Package

RECOMMENDED MOUNTING FOOTPRINT*

* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL. SOI DFRM/PD.

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

DOCUMENT NUMBER:	98ASB42985B	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	SC-88 2.00x1.25x0.90, 0.65P	PAGE 1 OF 2

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SC-88 2.00x1.25x0.90, 0.65P
CASE 419B-02
ISSUE Z

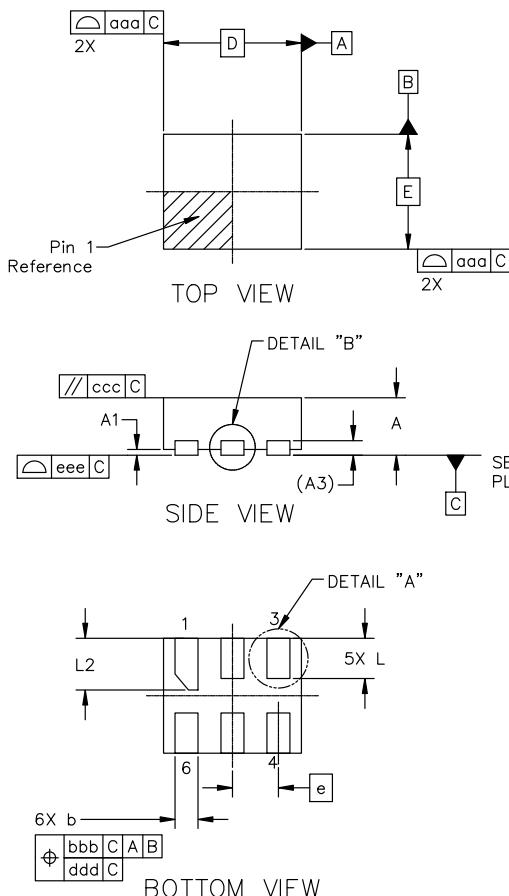
DATE 18 APR 2024

STYLE 1: PIN 1. Emitter 2 2. Base 2 3. Collector 1 4. Emitter 1 5. Base 1 6. Collector 2	STYLE 2: Cancelled	STYLE 3: Cancelled	STYLE 4: PIN 1. Cathode 2. Cathode 3. Collector 4. Emitter 5. Base 6. Anode	STYLE 5: PIN 1. Anode 2. Anode 3. Collector 4. Emitter 5. Base 6. Cathode	STYLE 6: PIN 1. Anode 2 2. N/C 3. Cathode 1 4. Anode 1 5. N/C 6. Cathode 2
STYLE 7: PIN 1. Source 2 2. Drain 2 3. Gate 1 4. Source 1 5. Drain 1 6. Gate 2	STYLE 8: Cancelled	STYLE 9: PIN 1. Emitter 2 2. Emitter 1 3. Collector 1 4. Base 1 5. Base 2 6. Collector 2	STYLE 10: PIN 1. Source 2 2. Source 1 3. Collector 1 4. Drain 1 5. Drain 2 6. Gate 2	STYLE 11: PIN 1. Cathode 2 2. Cathode 2 3. Anode 1 4. Cathode 1 5. Cathode 1 6. Anode 2	STYLE 12: PIN 1. Anode 2 2. Anode 2 3. Cathode 1 4. Anode 1 5. Anode 1 6. Cathode 2
STYLE 13: PIN 1. Anode 2. N/C 3. Collector 4. Emitter 5. Base 6. Cathode	STYLE 14: PIN 1. Vref 2. GND 3. GND 4. Iout 5. Ven 6. Vcc	STYLE 15: PIN 1. Anode 1 2. Anode 2 3. Anode 3 4. Cathode 3 5. Cathode 2 6. Cathode 1	STYLE 16: PIN 1. Base 1 2. Emitter 2 3. Collector 2 4. Base 2 5. Emitter 1 6. Collector 1	STYLE 17: PIN 1. Base 1 2. Emitter 1 3. Collector 2 4. Base 2 5. Emitter 2 6. Collector 1	STYLE 18: PIN 1. Vin1 2. Vcc 3. Vout2 4. Vin2 5. Gnd 6. Vout1
STYLE 19: PIN 1. Iout 2. Gnd 3. Gnd 4. Vcc 5. Ven 6. Vref	STYLE 20: PIN 1. Collector 2. Collector 3. Base 4. Emitter 5. Collector 6. Collector	STYLE 21: PIN 1. Anode 1 2. N/C 3. Anode 2 4. Cathode 2 5. N/C 6. Cathode 1	STYLE 22: PIN 1. D1 (l) 2. Gnd 3. D2 (l) 4. D2 (c) 5. Vbus 6. D1 (c)	STYLE 23: PIN 1. Vn 2. Ch1 3. Vp 4. N/C 5. Ch2 6. N/C	STYLE 24: PIN 1. Cathode 2. Anode 3. Cathode 4. Cathode 5. Cathode 6. Cathode
STYLE 25: PIN 1. Base 1 2. Cathode 3. Collector 2 4. Base 2 5. Emitter 6. Collector 1	STYLE 26: PIN 1. Source 1 2. Gate 1 3. Drain 2 4. Source 2 5. Gate 2 6. Drain 1	STYLE 27: PIN 1. Base 2 2. Base 1 3. Collector 1 4. Emitter 1 5. Emitter 2 6. Collector 2	STYLE 28: PIN 1. Drain 2. Drain 3. Gate 4. Source 5. Drain 6. Drain	STYLE 29: PIN 1. Anode 2. Anode 3. Collector 4. Emitter 5. Base/Anode 6. Cathode	STYLE 30: PIN 1. Source 1 2. Drain 2 3. Drain 2 4. Source 2 5. Gate 1 6. Drain 1

Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

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DESCRIPTION:	SC-88 2.00x1.25x0.90, 0.65P	PAGE 2 OF 2

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**GENERIC
MARKING DIAGRAM***


XX = Specific Device Code
M = Date Code

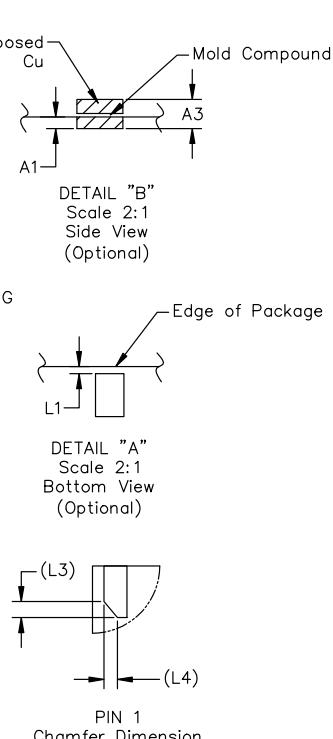
*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

**UDFN6, 1.20x1.00x0.50, 0.40P
CASE 517AA
ISSUE E**

DATE 09 MAY 2025

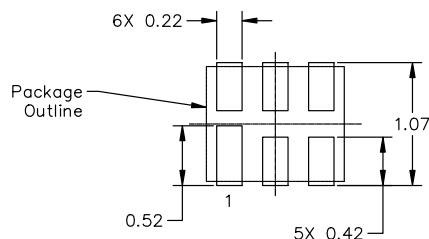
NOTES:

1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.



MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.45	0.50	0.55
A1	0.00	---	0.05
A3	0.127	REF	
b	0.15	0.20	0.25
D	1.20	BSC	
E	1.00	BSC	
e	0.40	BSC	
L	0.30	0.35	0.40
L1	0.00	---	0.15
L2	0.40	0.45	0.50
L3	0.14	REF	
L4	0.116	REF	

TOLERANCE FORM & POSITION		
aaa	0.10	
bbb	0.10	
ccc	0.10	
ddd	0.05	
eee	0.08	

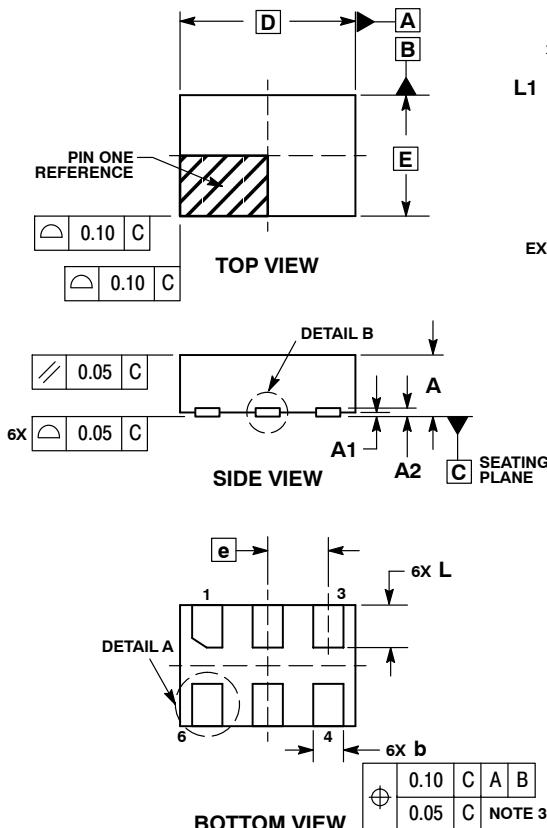


RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

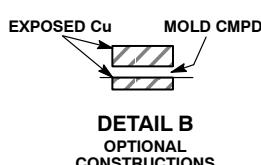
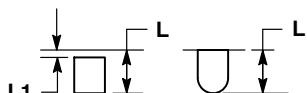
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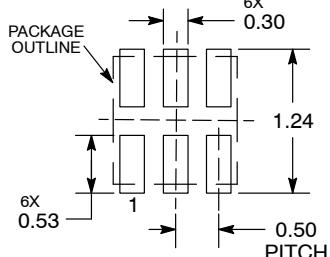
UDFN6, 1.45x1.0, 0.5P
CASE 517AQ
ISSUE O

DATE 15 MAY 2008



DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A2	0.07 REF	
b	0.20	0.30
D	1.45 BSC	
E	1.00 BSC	
e	0.50 BSC	
L	0.30	0.40
L1	---	0.15

MOUNTING FOOTPRINT



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



X = Specific Device
Code

M = Date Code
*This information is generic. Please refer to device data sheet for actual part marking.
Pb-Free indicator, "G" or microdot "■", may or may not be present.

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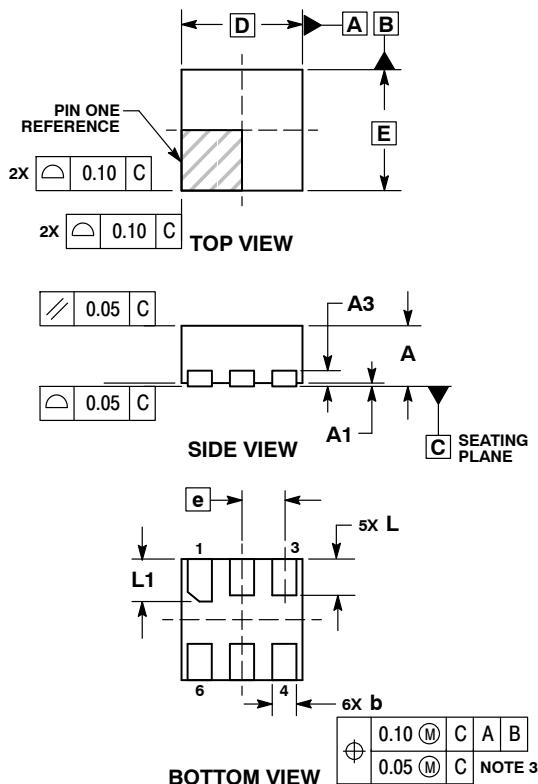
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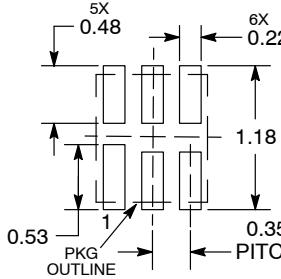
SCALE 4:1

UDFN6, 1x1, 0.35P
CASE 517BX
ISSUE O

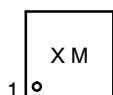
DATE 18 MAY 2011



DIM.	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13	REF
b	0.12	0.22
D	1.00	BSC
E	1.00	BSC
e	0.35	BSC
L	0.25	0.35
L1	0.30	0.40

RECOMMENDED
SOLDERING FOOTPRINT*

*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC
MARKING DIAGRAM*

X = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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